



Application No.: 10/612,804

Amendment After Allowance dated: October 3, 2005

### AMENDMENTS TO THE CLAIMS

1-2 (Cancelled)

3. (Original) A method, comprising:

forming a conductive bump on one of a die and a substrate;

forming a non-conductive pocket on the other of said die and substrate; and

contacting the bump with the non-conductive pocket; and

curing the bump and the non-conductive pocket to form a covalently bonded laminate

structure.

4. (Original) The method of claim 3, wherein said step of forming the conductive bump

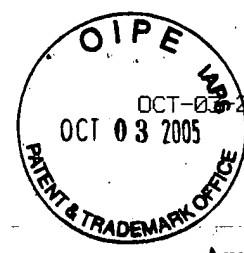
includes forming the bump using a polymer.

5-17 (Cancelled)

18. (Currently Amended) A method for making a flip chip apparatus, comprising:

forming a plurality of electrically conductive polymer bumps on one of a die and a substrate;

forming an electrically non-conductive film around each of a plurality of contact pads on other of said die and substrate;



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partially curing the bumps and the film; and  
contacting the bumps with the contact pads, and curing the bumps and the non-conductive  
film to form a covalently bonded laminate structure.

19. (Original) The method of claim 18 wherein the bumps and the film being formed from  
materials allowing control of the degree of latency of the bumps.

20. (Original) The method of claim 18, wherein the materials include benzocyclobutene.

21. (Original) The method of claim 18, wherein the covalently bonded structure being  
formed of materials having equivalent coefficients of thermal expansion.

22. (Original) The method of claim 18, wherein said step of forming the polymer bumps  
includes forming the bumps using one of spin coating and stencil printing.

23-27 (Cancelled)